

Aries

CSP center probe socket

DC Measurement Results

prepared by

Gert Hohenwarter

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Objective

The objective of these measurements is to determine the DC performance of an Aries CSP center probe socket. Measurements are to determine parameters relevant to test applications. Among those are current carrying ability, contact resistance and leakage as a function of voltage.

Methodology

A four terminal (Kelvin) measurement setup is used that includes a computer controlled voltage source capable of delivering 10 A. The voltage developed across the contact is measured with a HP 3456A DMM and yields a V-I record.

Contact resistance testing as a function of displacement is performed in a test fixture with a calibrated LDT linked to the data acquisition system and the same 4 terminal measurement setup as used for the V-I-curve determination.

Leakage testing relies on acquisition of a large number of data points with subsequent averaging to reduce noise as much as possible. In this manner, pA leakage currents can be detected.

For leakage measurements the shorting plate on the DUT side is removed and an excitation applied to the connection under test.

The CSP center probe socket is held in a fixture consisting of insulating material similar to the one shown in Fig. 2:



Figure 2 CSP center probe socket mounting plate example

Leakage testing is performed via computer controlled voltage source and DMM. Voltage is increased in small steps and the associated current is recorded. From these values, resistance is computed.

Measurements

Resistance

The resistance as a function of deflection is an important quantity since it testifies to the minimum compression required to achieve a valid and stable electrical connection. The observed curve for the Aries CSP center probe socket is shown below:

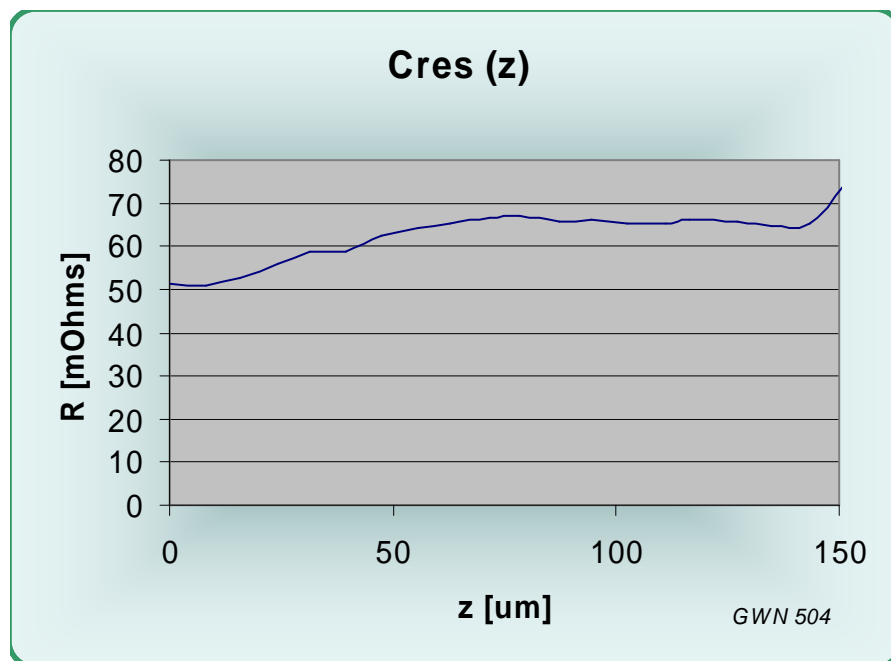


Figure 3 Contact resistance as a function of displacement

This measurement includes the contact resistance at the pads (C_{res}) and the dc resistance of the contact itself. For this graph, the value $z=0$ represents the maximum compression in operation, i.e. with the DUT fully inserted.

Current carrying capability

The measured current – voltage relationship for the CSP center probe socket shows a linear slope:

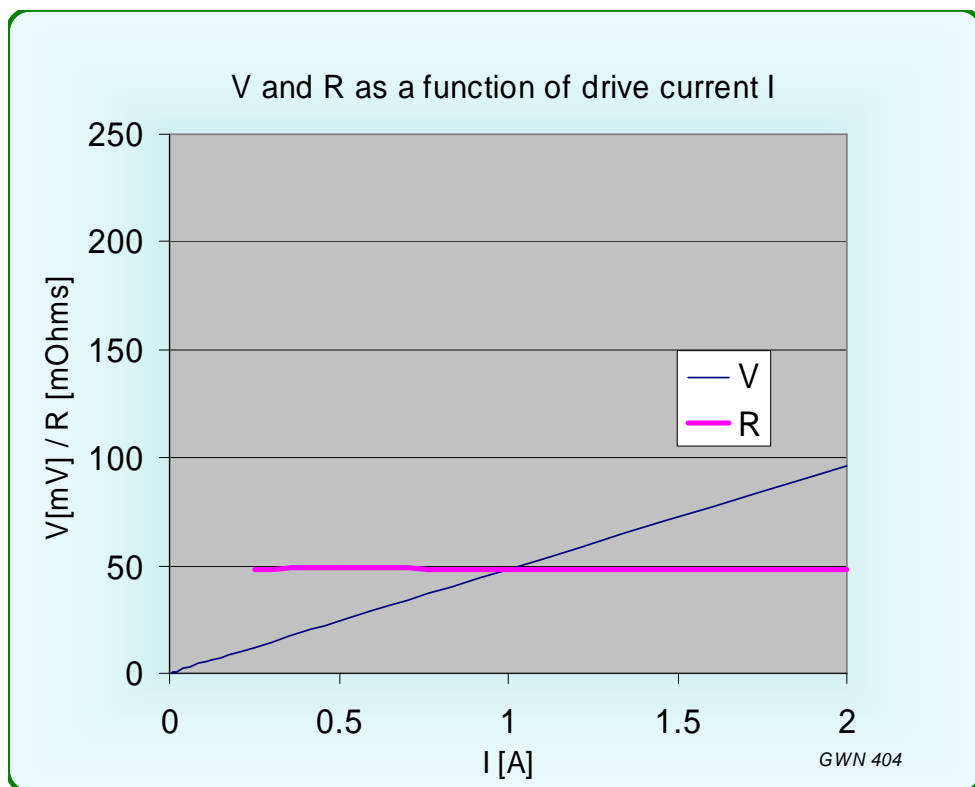


Figure 4 Voltage and resistance as a function of drive current

There are no anomalies in this response. The slight resistance rise at the low end is due to inaccuracies in the 10A current source at extremely low current settings.

The accompanying power dissipation in the connection exceeds 100mW at currents above about 1.4A:

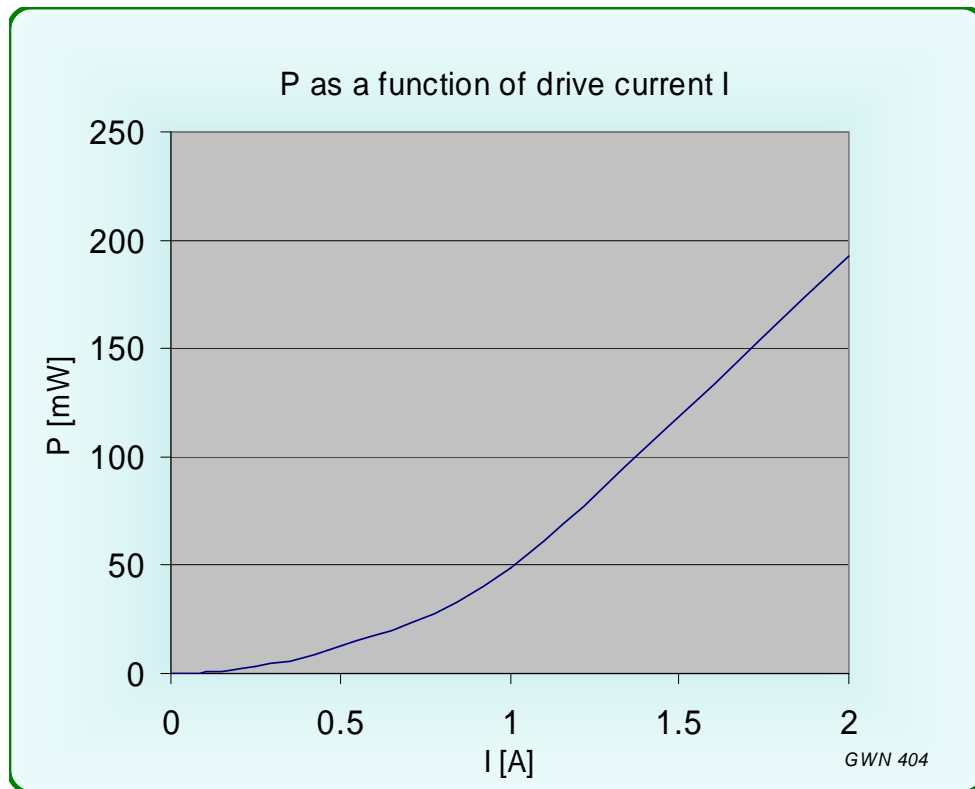


Figure 5 Power dissipation as a function of drive current

Leakage current

Any conductive path between contacts can and will cause difficulties for accurate testing of devices with high input impedances. Thus, leakage current was measured as a function of excitation voltage between two adjacent connections:

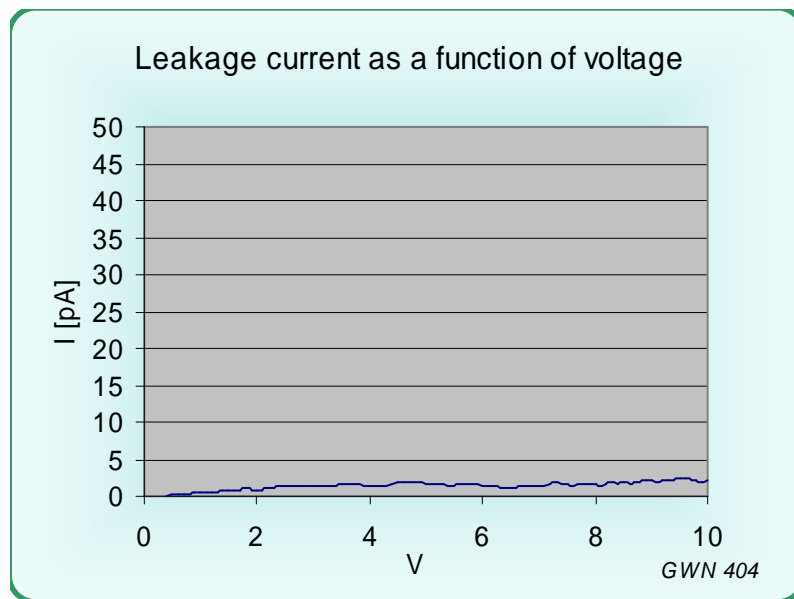


Figure 6 Leakage current as a function of drive voltage

Leakage is very low and is at the system limits.

When computing the corresponding resistance, very large values result:

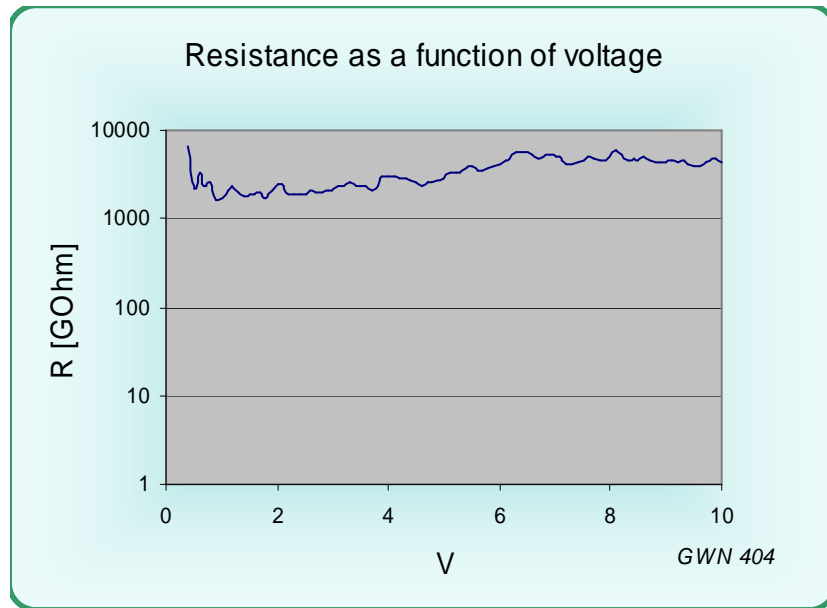


Figure 7 Leakage resistance as a function of drive voltage

The resistance values are well above 1000 GigaOhms for all excitation voltages.